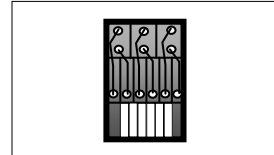
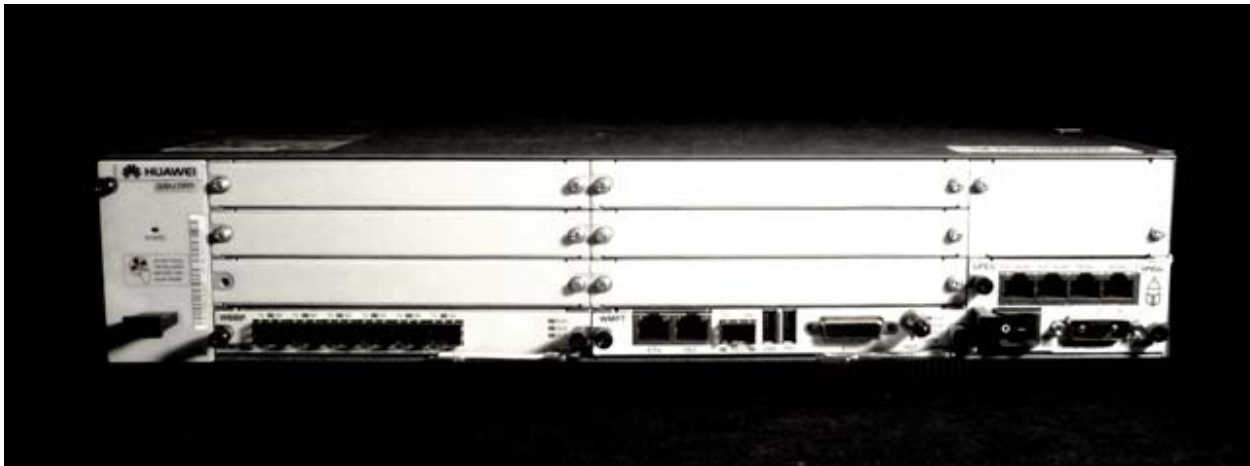


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Huawei W-CDMA/HSPA Baseband Unit WD2BBUC-HERT BBU Model BBU3900

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